Stock Code: **7828**

INNOS
創新服務股份有限公司

Innostar Service Inc.

Q1 2026 Operations Overview & Outlook

2026/6

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1.Company Overview & Philosophy

INNOS empowers your manufacturing process and product innovation with expert, end-to-end solutions

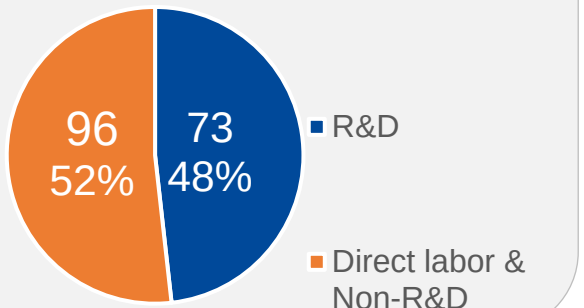
Company Overview

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創新服務股份有限公司
InnoStar Service, Inc.

- **Established: 2004**
- **Capital:** NTD 405 million
- **Employees:** 169
- (as of April 2026)
- **Locations**
  - Hsinchu Plant
  - Taichung Headquarters
  - Kaohsiung Office
- **Core Businesses**
  - Development, manufacturing, and sales of semiconductor automation equipment
  - Advanced packaging solutions
  - Development, manufacturing, and sales of advanced packaging components
  - Probe card repair services and sales of related materials

R&D talent accounts for **43%** of total headcount.





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Key Milestones

2004
- Company established
- Launched first-gen automatic plastic lens-cutting machine
- **Pioneered automation revolution for optical industry**

2014
- **Expanded into advanced semiconductor testing, developed MEMS Probe Card Assembly Equipment for wafer testing**
- **Pioneered automation revolution for probe card industry**

2016
OEM service of MEMS probe assembly for leading foundries, having processed more than 300 million units

2022
Auto Probe Assembly Machine adopted by leading probe card makers

2024
High-density Cu Pillar applied to WIFI modules with substantial sample shipments

Probe Assembly Machine adopted at scale by probe card makers



2025
High-density Cu Pillar applied to power modules, TGV, and PLP modules
- **Technoprobe became strategic investor**
- **Launched comprehensive MEMS probe card automation solutions**



2026
To verify and mass-produce High-density Cu Pillar modules
- **To expand the MEMS probe card equipment lineup**
- **To establish and realize probe card repair capacity**

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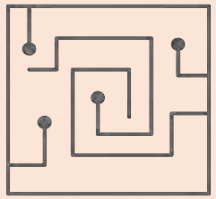
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2. Industry & Operations Overview

Industry Overview

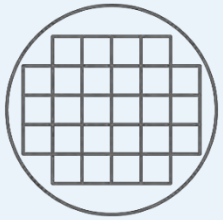
Upstream



IC Design

Foundry

Midstream

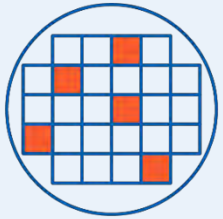


IC/Wafer Manufacturing

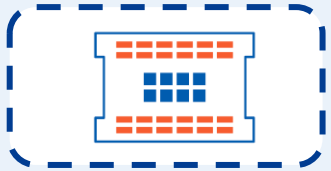
Process & Testing Equipment

Photomask

Chemical



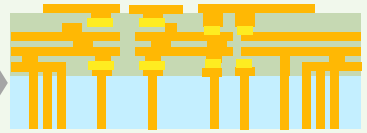
IC Testing (Chip Probing)



Probe Cards for Wafer Testing

Downstream





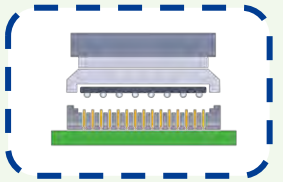
IC Packaging

IC Testing

Process & Testing Equipment

Substrate

Lead Frame



Final Test

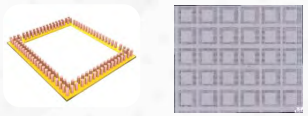
IC Distribution



Probe Assembly and Related Automation Equipment



CoWoS Substrate Component Repair Equipment



High-density Cu Pillar Modules



Pogo Pin Assembly & Related Automation Equipment

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Product Portfolio

Probe Card Full-Line Equipment Automation Solutions

- Laser Drilling Machine
- Guide Plate Inspection and Lamination Machine
- Dual-arm Needle Assembly Machine
- Probe Card Inspection Machine
- Laser Reshaping Machine, Laser Cleaning Machine
- Auto Probe Change Machine
- Probe Binning and Aligning Machine
- CoWoS FT Auto Probe Assembly (90um) and Inspection Machine



MEMS Probe Card Repair Lineup

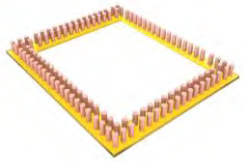
Semiconductor High-Precision Processing

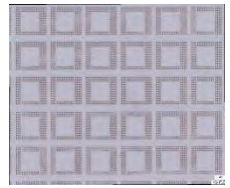
- High-Precision Laser Cutting Machine
- Mini LED Laser Repair Equipment
- Laser De-coating Machinery
- MEMS Mirrors Precision Assembly Machine
- CoWoS Substrate Component Repair Equipment
- High-Precision Spot Welding Machine

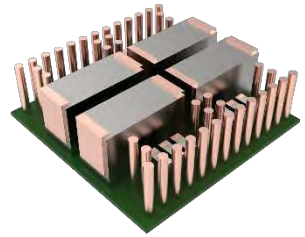


Advanced Packaging

- High-Density Cu Pillar Module for WiFi modules
- High-Density Cu Pillar Module for power modules
- Interposer (10:1) Cu Pillar TGV







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End-to-End Automation Solutions for MEMS Probe Cards

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INNOS End-to-End Probe Card Manufacturing and Repair Equipment

Laser Drilling Machine (LS-11)	Guide Plate Inspection and Lamination Machine (PHIA-02)	Dual-arm Needle Assembly Machine (AT-105)	Probe Card Inspection Machine (PCR-01)	Laser Reshaping Machine (PHR02) & Laser Cleaning Machine (PHC-02)	Auto Probe Change Machine (PIR-02)	Probe Binning and Aligning Machine (PSA-01)
Development completed	Completion expected 1Q26	Development completed	Development completed	Development completed	Development completed	Development completed



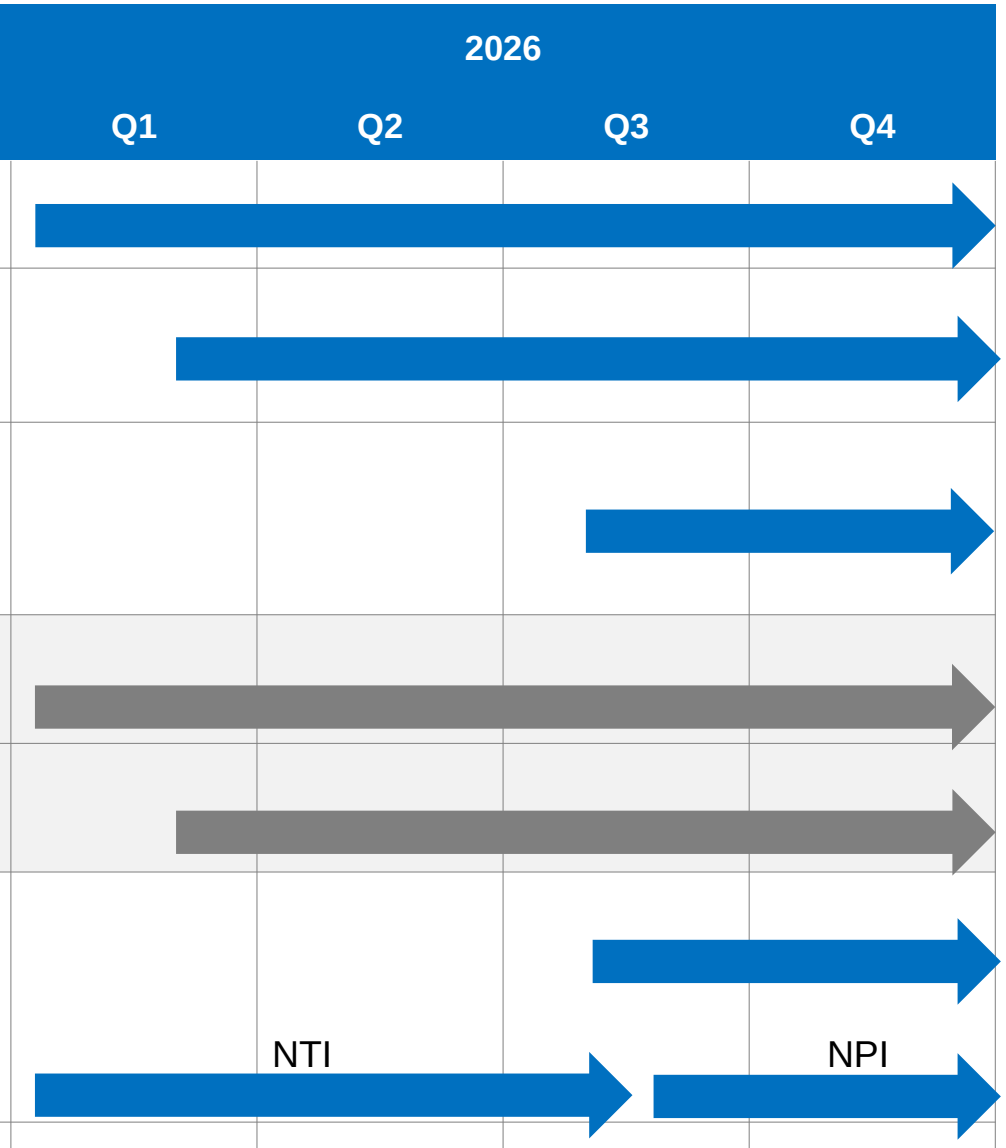
Conventional Probe Card Manufacturing Processes

Laser drilling machine	Manual & semi-auto lamination	Manual needle assembly	Manual microscopic inspection	Semi-auto laser cleaning	Manual probe replacement & measurement	Manual binning

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Three-Pillar Product Lines

#	INNOS'MEMS Probe Card Solutions	Customers
Automated Probe Card Equipment	1. Dual-arm Probe Assembly machine	TP Group
	2. Probe Card Repair Lineups: Probe replacement, probe reshaping, probe card inspection, laser cleaning, and sorting & alignment machines.	TP Group
	3. Probe Card Automation Processing Equipment: Laser drilling, automated alignment & lamination, reshaping, electrical testing, and pin adjustment machines.	TP Group
Material Kits & Contract Service	1 Probe Card Contract Service: pin insertion/reshaping/repair	TP Alliance
	2. Probe Card Material Kits	TP Alliance
Cu Pillar Products	1. Cu Pillar Modules: AiP, power modules	Wearable device manufacturer Array Antenna Module Manufacturers Power supply PMMIC Module Manufacturer
	2. TVG-ICP (Cu pillar inserted) core layer substrates	AI networking chip vendors



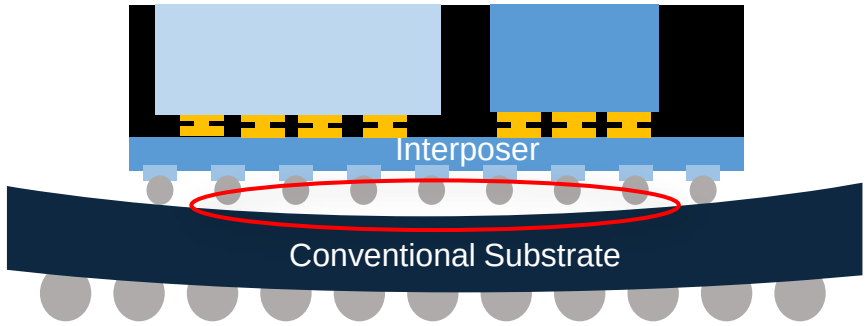
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INNOS

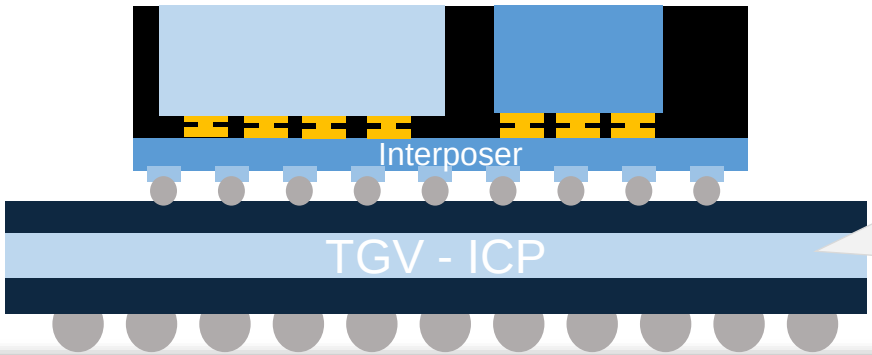
TGV-ICP (Through Glass Via with Inserted Cu Pillar)

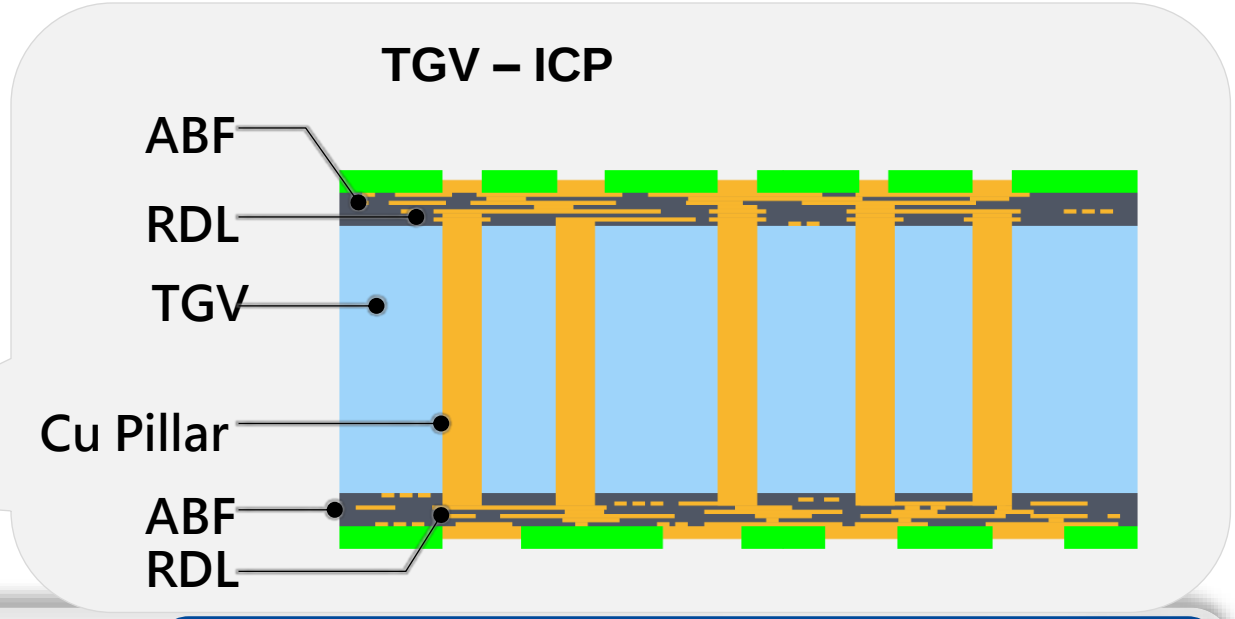
TGV – ICP for substrates addresses critical large-form-factor demands across CoWoS (-S/R/L), CoPoS, and other advanced packaging processes.

Traditional organic substrates tend to warp due to large differences in the coefficients of thermal expansion (CTE) among their multilayer materials.



Glass-substrate TGV-ICP delivers high rigidity and zero warpage.

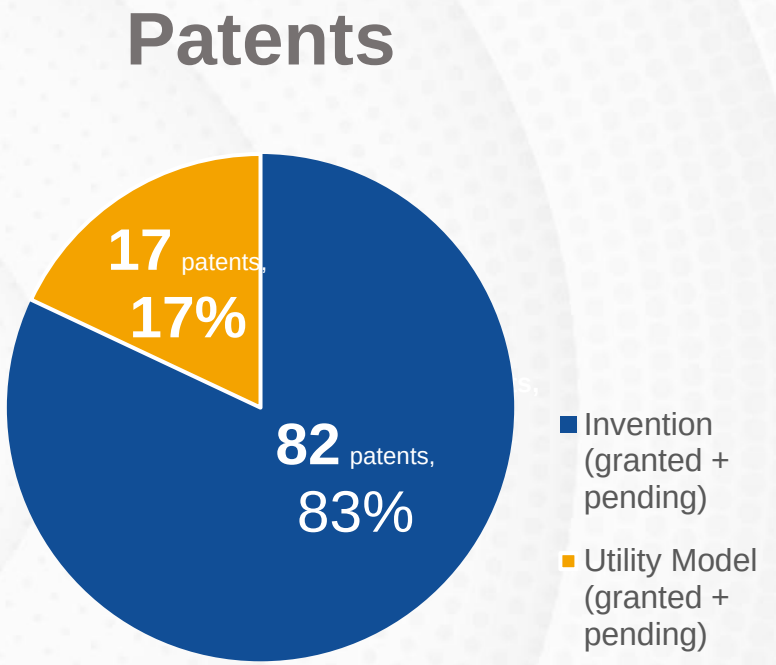




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Patents

Patent Category	Granted		Pending	
	Invention	Utility Model	Invention	Utility Model
Semiconductor advanced process equipment	15	1	5	1
Advanced packaging equipment and related products	14	7	23	0
Others	14	8	11	0
Subtotal	43	16	39	1



As of now, INNOS holds 59 patents (43 inventions and 16 utility model patents), with 40 additional applications pending (39 inventions and 1 utility model patents).

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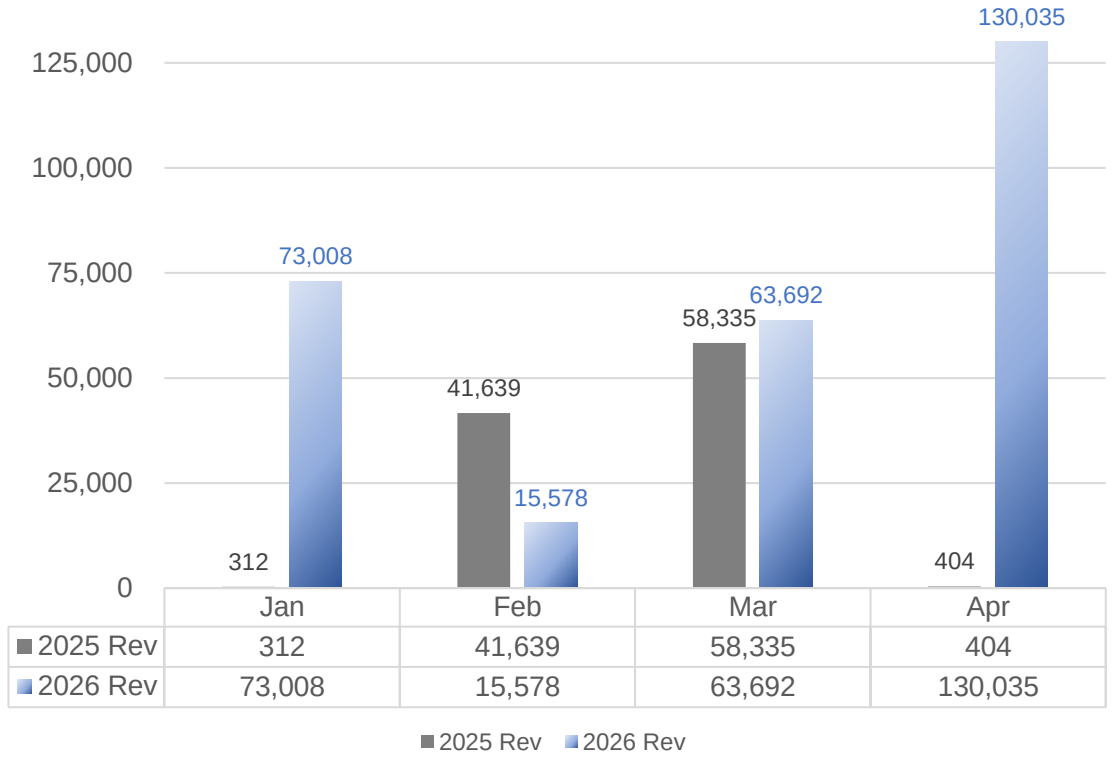
3. 1Q26 Performance & Outlook

Operating Performance

Unit: NTD thousands; NTD

	Q1 2025	Q4 2025	Q1 2026
Revenue	100,286	394,369	**152,278**
Gross margin	61.80%	79.36%	**80.18%**
Operating margin	15.43%	51.11%	**25.30%**
EPS	0.49	4.91	**1.02**
EBITDA margin	28.48%	55.83%	**37.80%**

Unit: NTD thousands



- 1Q26 revenue grew 51.84% YoY, driven primarily by the evolution of advanced semiconductor processes and robust end-user demand for AI applications. Following the development of our Dual-arm Probe Assembly Machine for MEMS probe cards and full-line automation solutions, steady shipments of MEMS probe card equipment continued, sustaining strong gross margins and revenue growth.
- 1Q26 operating expenses increased YoY mainly due to revenue growth, workforce expansion, and higher provisions for employee bonuses, performance incentives, and director compensation tied to the company's increased revenue and profitability.

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Outlook:
Three Core Pillars for Operational Growth

Semiconductor Equipment

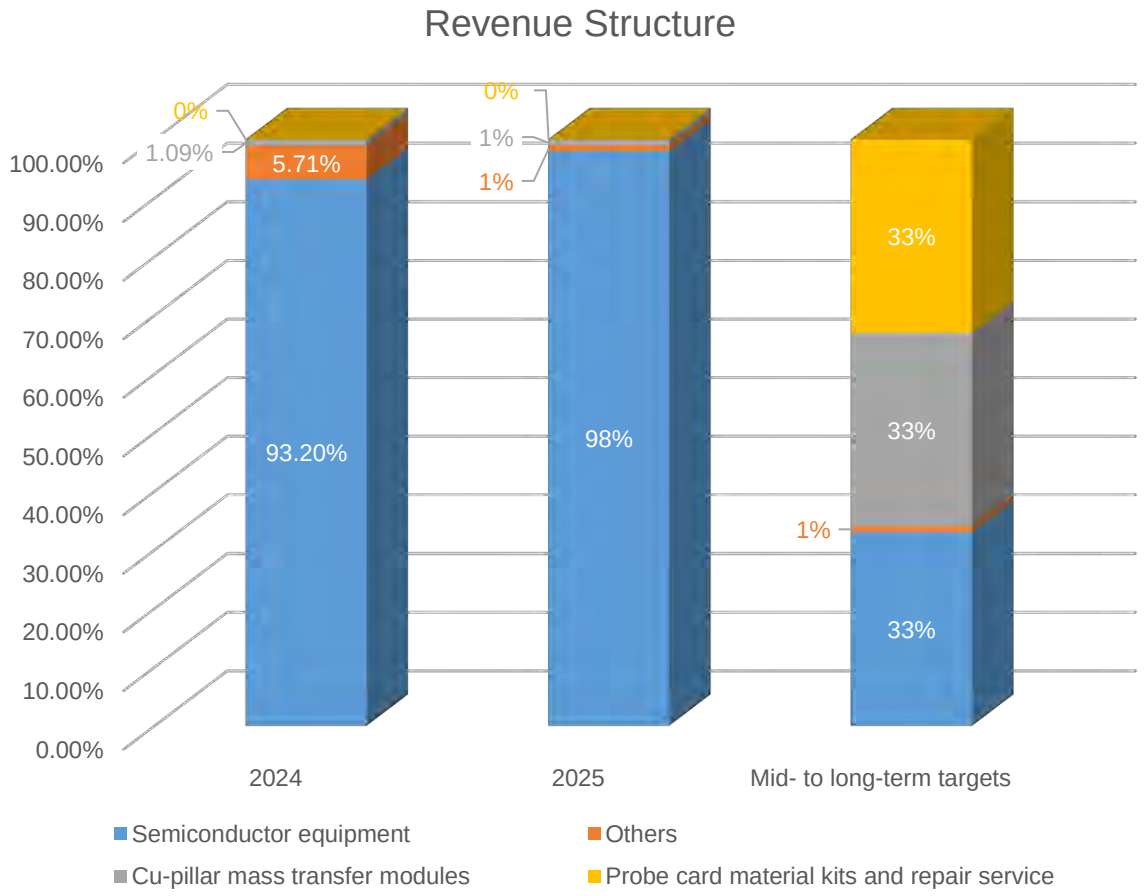
- Demand from end customers for Dural-arm probe assembly machines is strengthening, driven by continued market growth. As a result, future shipments are expected to increase significantly on a positive trajectory.
- Automation equipment related to probe card repair has completed validation in several products and is now entering shipment phase. This is expected to contribute a new round of growth momentum in the second half of 2026.
- A new generation of advanced probe card-related equipment is currently under development. Validation will be carried out sequentially in the second half of the year, with contributions to revenue expected in 2027.

Probe Card Material Kits and Repair Service

- Successfully implemented at several leading probe card manufacturers, introducing TP MEMS probes and providing subsequent repair and maintenance services.
- An automated repair production line has been established, enabling customers to receive fast and highly efficient refurbishment services, significantly reducing lead time.

Cu Pillar Mass Transfer Modules

- Our cu pillar solutions targeting the power module market, as well as advanced packaging applications such as TGV and CoWoS.
- Mass production of copper pillar modules is expected to begin by the end of 2026, with applications including antenna-in-package (AiP), power modules, and communication modules for wearable devices such as true wireless stereo (TWS) earphones.
- By the end of 2027, gradual mass production of TGV-ICP core glass substrate products is expected, targeting high-speed data transmission semiconductor packaging applications.



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